

DATA SHEET

74LVC11

Triple 3-input AND gate

Product specification
Supersedes data of 1998 Apr 28

2004 Jan 13

Triple 3-input AND gate

74LVC11

FEATURES

- Wide supply voltage range from 1.2 to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Output capability: standard
- I_{CC} category: SSI
- In accordance with JEDEC standard no. 8-1A
- ESD protection:
HBM EIA/JESD22-A114-A exceeds 2000 V
MM EIA/JESD22-A115-A exceeds 200 V.

DESCRIPTION

The 74LVC11 is a high-performance, low power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

The 74LVC11 provides the 3-input AND function.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25\text{ }^{\circ}\text{C}$; $t_r = t_f \leq 2.5\text{ ns}$.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	propagation delay nA, nB, nC to nY	$C_L = 50\text{ pF}$; $V_{CC} = 3.3\text{ V}$	3.7	ns
C_I	input capacitance		5.0	pF
C_{PD}	power dissipation capacitance per gate	notes 1 and 2	26	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

N = total switching outputs;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

2. The condition is $V_I = \text{GND to } V_{CC}$.

ORDERING INFORMATION

TYPE NUMBER	TEMPERATURE RANGE	PACKAGE			
		PINS	PACKAGE	MATERIAL	CODE
74LVC11D	-40 to +85 $^{\circ}\text{C}$	14	SO14	plastic	SOT108-1
74LVC11DB	-40 to +85 $^{\circ}\text{C}$	14	SSOP14	plastic	SOT337-1
74LVC11PW	-40 to +85 $^{\circ}\text{C}$	14	TSSOP14	plastic	SOT402-1
74LVC11BQ	-40 to +85 $^{\circ}\text{C}$	14	DHVQFN14	plastic	SOT762-1

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FUNCTION TABLE

See note 1.

INPUT			OUTPUT
nA	nB	nC	nY
L	L	L	L
L	L	H	L
L	H	L	L
L	H	H	L
H	L	L	L
H	L	H	L
H	H	L	L
H	H	H	H

Note

1. H = HIGH voltage level.
L = LOW voltage level.

PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	1B	data input
3	2A	data input
4	2B	data input
5	2C	data input
6	2Y	data output
7	GND	ground (0 V)
8	3Y	data output
9	3A	data input
10	3B	data input
11	3C	data input
12	1Y	data output
13	1C	data input
14	V _{CC}	positive supply voltage

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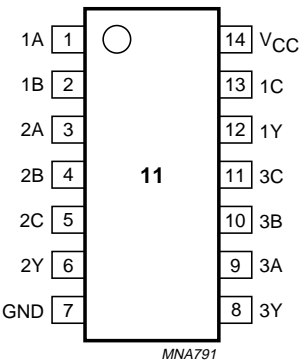
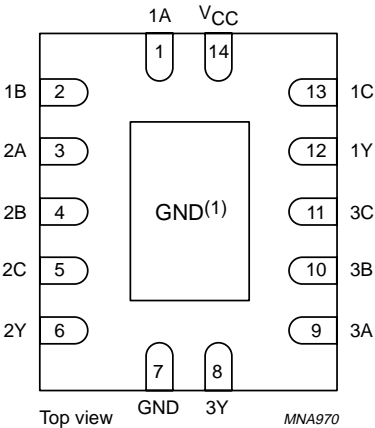


Fig.1 Pin configuration SO14 and (T)SSOP14.



(1) The die substrate is attached to this pad using conductive die attach material. It can not be used as a supply pin or input.

Fig.2 Pin configuration DHVQFN14.

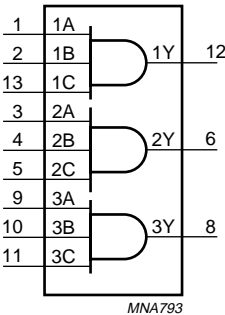


Fig.3 Logic symbol.

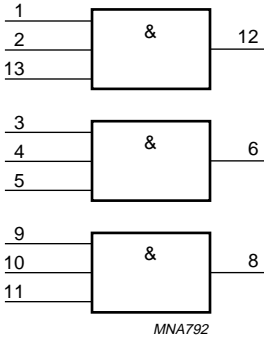


Fig.4 Logic symbol (IEEE/IEC).

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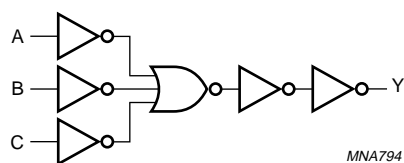


Fig.5 Logic diagram (one gate).

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage	for maximum speed performance	2.7	3.6	V
		for low-voltage applications	1.2	3.6	V
V_I	input voltage		0	5.5	V
V_O	output voltage		0	V_{CC}	V
T_{amb}	operating ambient temperature		-40	+85	°C
t_r, t_f	input rise and fall times	$V_{CC} = 1.2$ to 2.7 V	0	20	ns/V
		$V_{CC} = 2.7$ to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input diode current	$V_I < 0$	—	-50	mA
V_I	input voltage	note 1	-0.5	+6.5	V
I_{OK}	output diode current	$V_O > V_{CC}$ or $V_O < 0$	—	±50	mA
V_O	output voltage	note 1	-0.5	$V_{CC} + 0.5$	V
I_O	output source or sink current	$V_O = 0$ to V_{CC}	—	±50	mA
I_{GND}, I_{CC}	V_{CC} or GND current		—	±100	mA
T_{stg}	storage temperature range		-65	+150	°C
P_{tot}	power dissipation	$T_{amb} = -40$ to $+125$ °C; note 2	—	500	mW

Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. For SO14 packages: above 70 °C the value of P_D derates linearly with 8 mW/K.
 For (T)SSOP14 packages: above 60 °C the value of P_D derates linearly with 5.5 mW/K.
 For DHVQFN14 packages: above 60 °C the value of P_D derates linearly with 4.5 mW/K.

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DC CHARACTERISTICS

At recommended operating conditions voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. ⁽¹⁾	MAX.	UNIT
		OTHER	V _{CC} (V)				
T _{amb} = -40 °C to +85 °C							
V _{IH}	HIGH level input voltage		1.2	V _{CC}	–	–	V
			2.7 to 3.6	2.0	–	–	V
V _{IL}	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}					
		I _O = -12 mA	2.7	V _{CC} - 0.5	–	–	V
		I _O = -100 μA	3.0	V _{CC} - 0.2	V _{CC}	–	V
		I _O = -12 mA	3.0	V _{CC} - 0.6	–	–	V
		I _O = -24 mA	3.0	V _{CC} - 1.0	–	–	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}					
		I _O = 12 mA	2.7	–	–	0.40	V
		I _O = 100 μA	3.0	–	GND	0.20	V
		I _O = 24 mA	3.0	–	–	0.55	V
I _{LI}	input leakage current	V _I = 5.5 V or GND	3.6	–	±0.1	±5	μA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0	3.6	–	0.1	10	μA
ΔI _{CC}	additional quiescent supply current per input pin	V _I = V _{CC} - 0.6 V; I _O = 0	2.7 to 3.6	–	5	500	μA

Note1. All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.**AC CHARACTERISTICS**GND = 0 V; t_r = t_f ≤ 2.5 ns; C_L = 50 pF; R_L = 500 Ω.

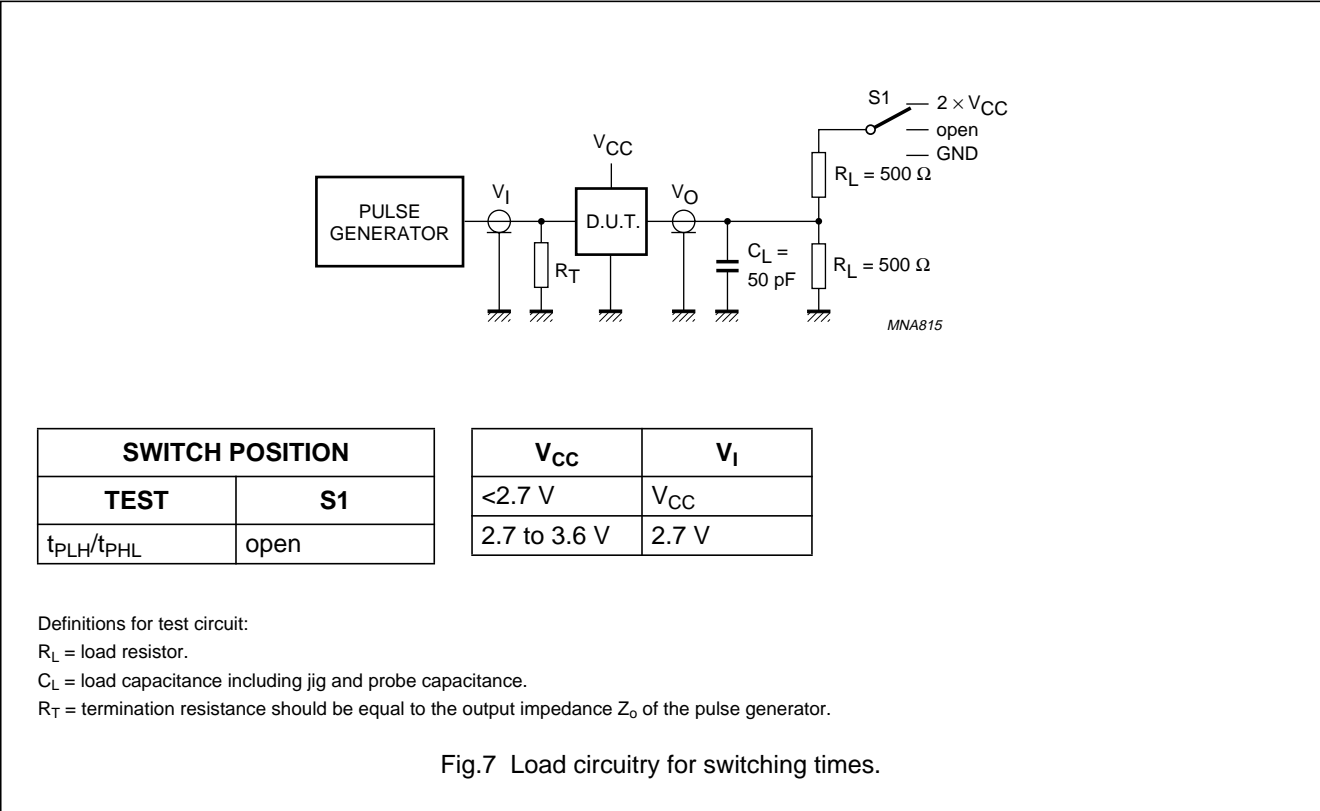
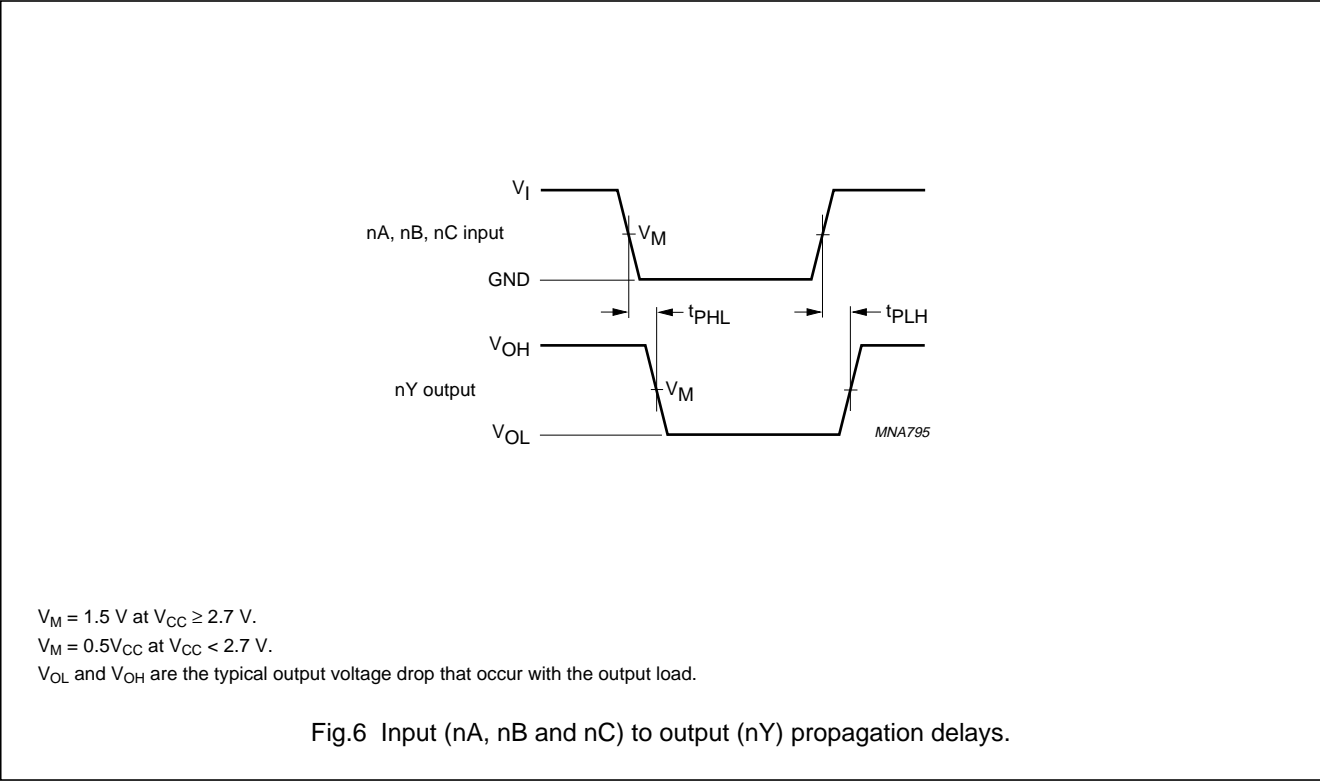
SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. ⁽¹⁾	MAX.	UNIT
		WAVEFORMS	V _{CC} (V)				
T _{amb} = −40 to +85 °C							
t _{PHL} /t _{PLH}	propagation delay	see Figs 6 and 7	2.7	–	–	7.0	ns
			3.0 to 3.6	–	3.7	6.2	ns

Note1. Typical value is measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

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AC WAVEFORMS



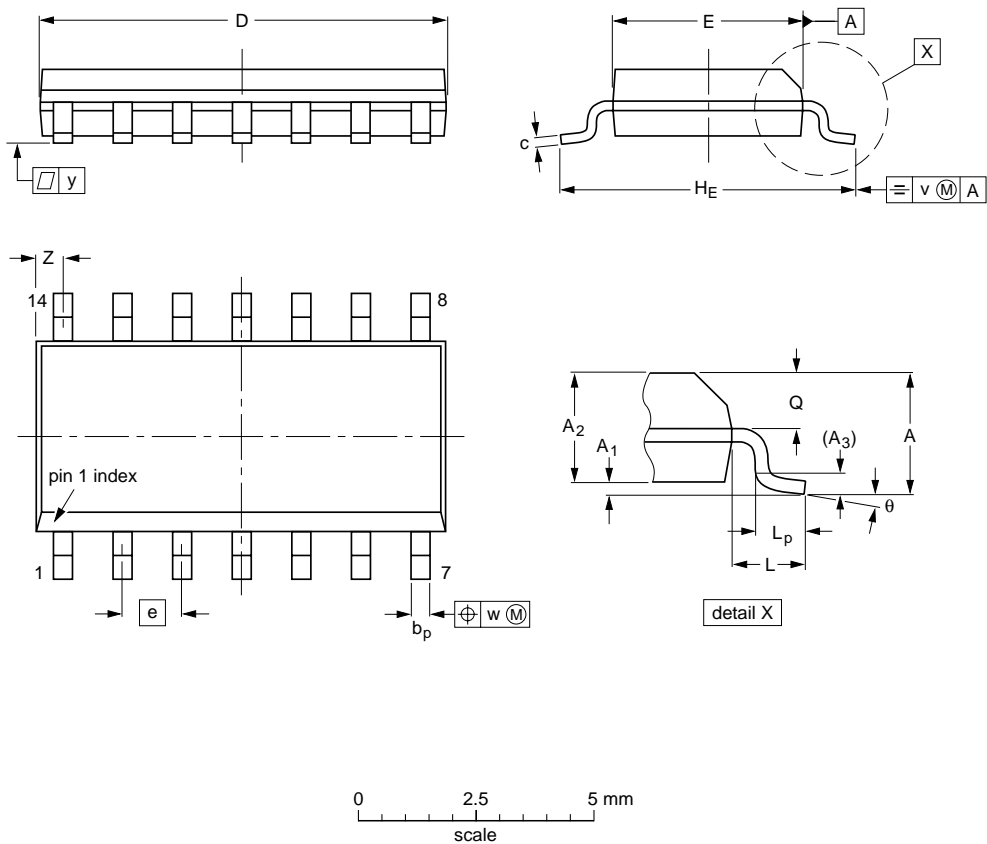
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PACKAGE OUTLINES

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

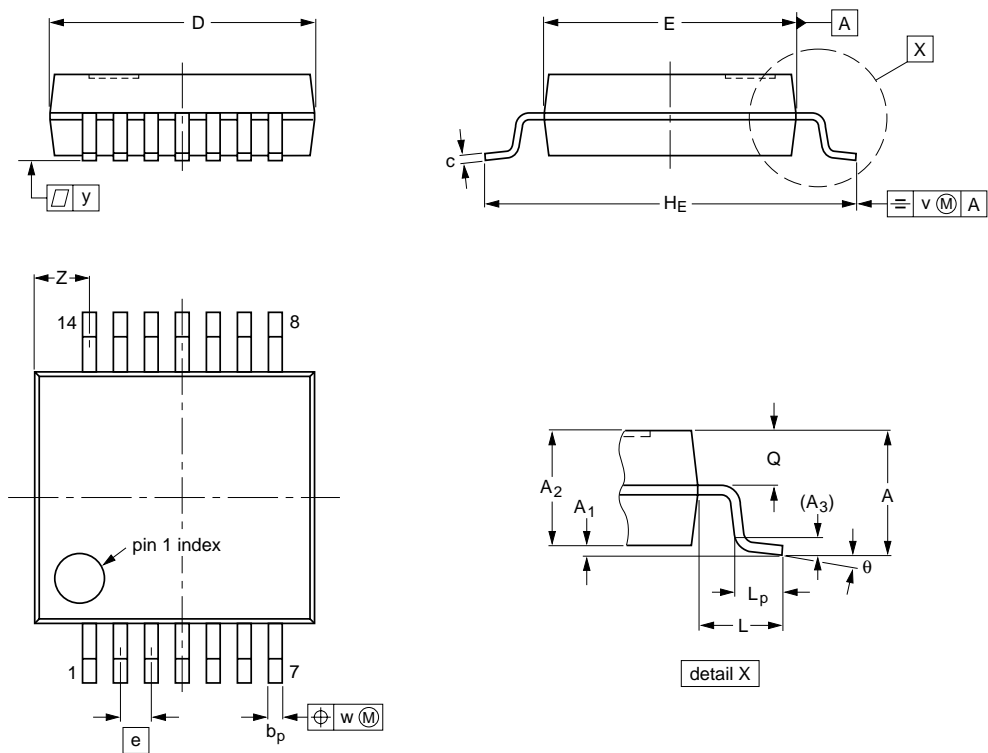
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-1	076E06	MS-012				99-12-27 03-02-19

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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

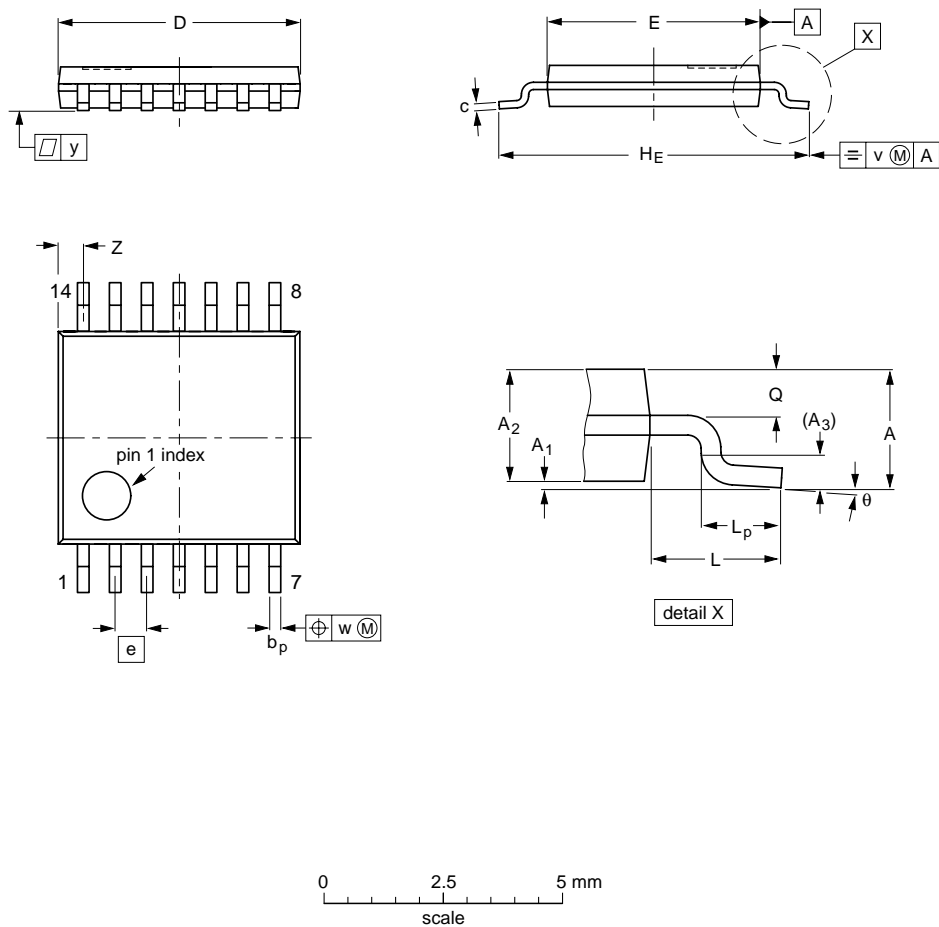
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT337-1		MO-150				99-12-27 03-02-19

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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

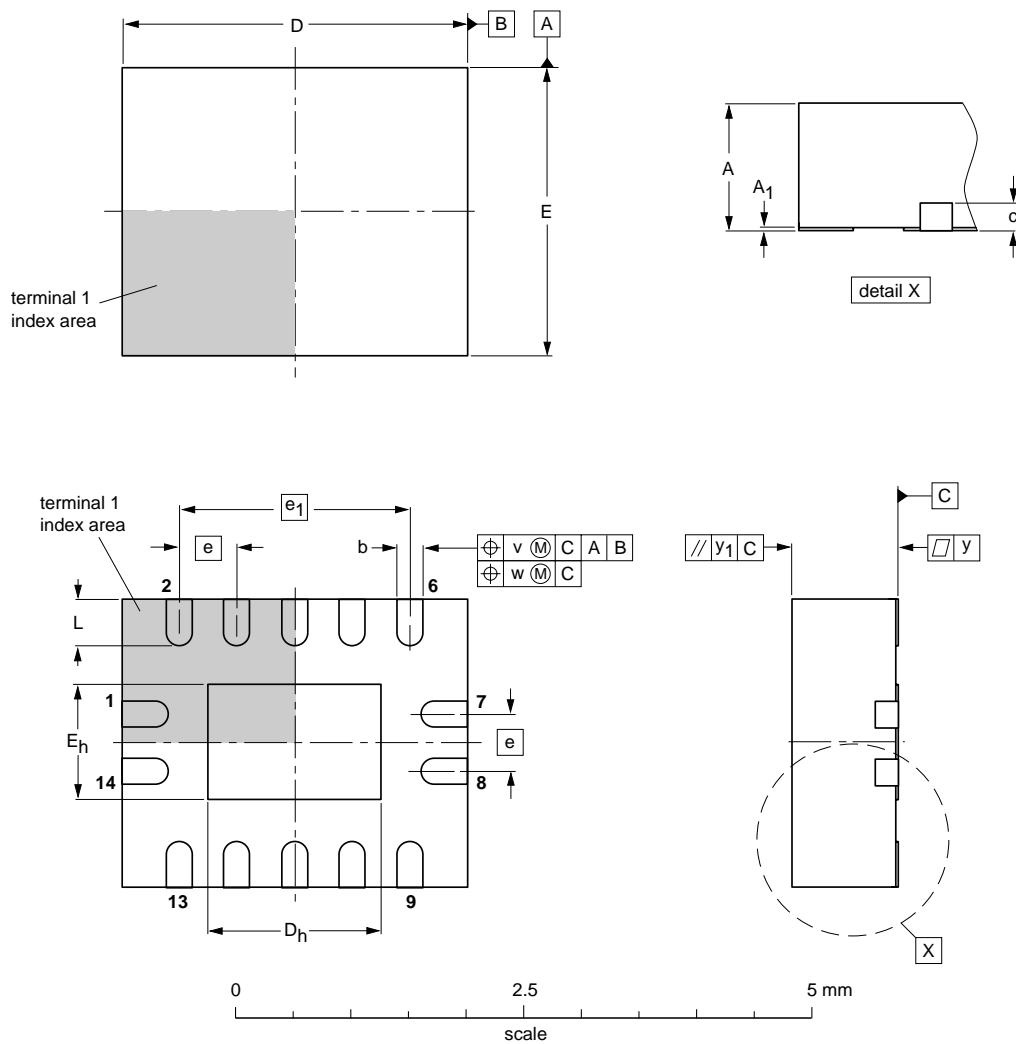
- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				99-12-27 03-02-18

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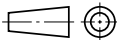
DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	L	v	w	y	y ₁
mm	1	0.05 0.00	0.30 0.18	0.2	3.1 2.9	1.65 1.35	2.6 2.4	1.15 0.85	0.5	2	0.5 0.3	0.1	0.05	0.05	0.1

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT762-1	---	MO-241	---			02-10-17 03-01-27

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